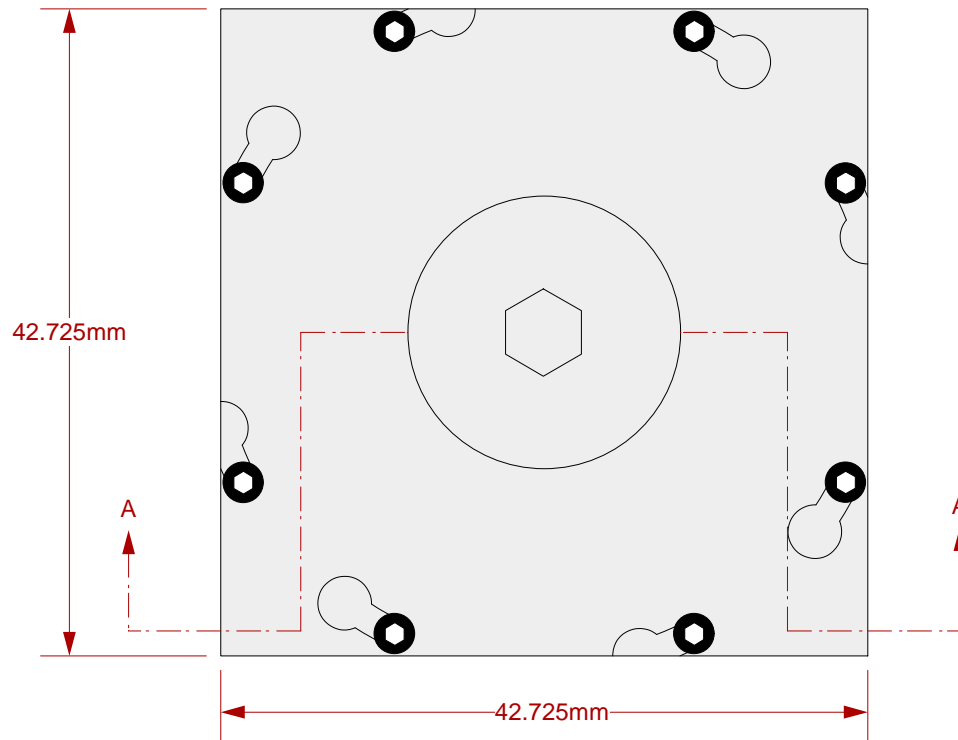


GHz BGA Socket - Direct mount, solderless

Features

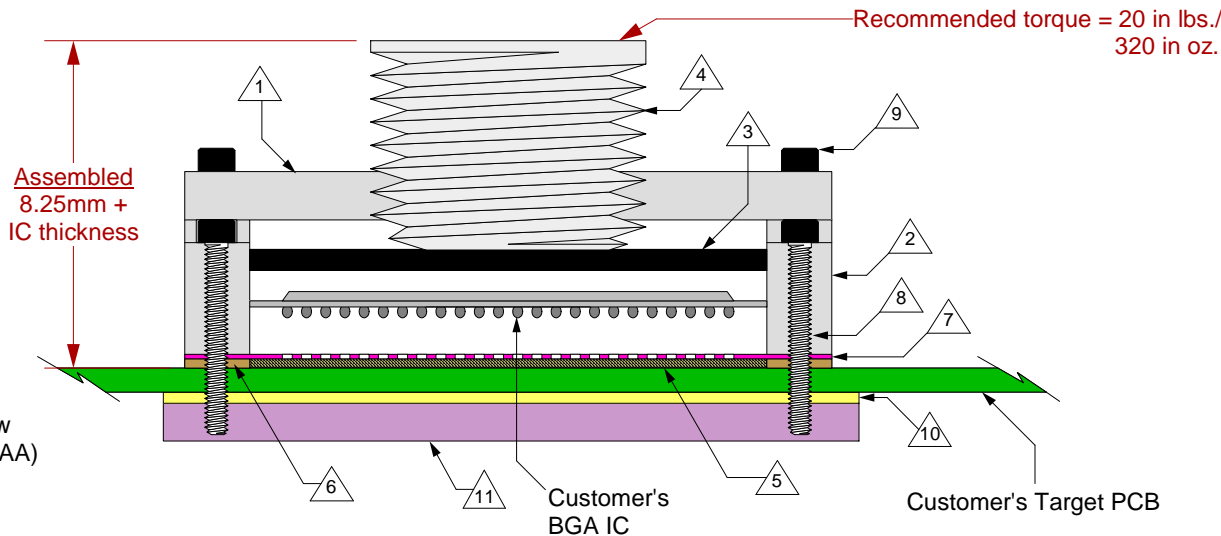
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Top View



42.725mm

42.725mm



Side View
(Section AA)

Assembled
8.25mm +
IC thickness

Recommended torque = 20 in lbs./
320 in oz.

Customer's
BGA IC

Customer's Target PCB

- 1 Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm.

- 2 Socket base: Black anodized Aluminum.
Thickness = 5mm.

- 3 Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm.

- 4 Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm.

- 5 Elastomer: 40 micron dia gold plated brass
filaments arranged symmetrically in a silicone
rubber (63.5 degree angle).
Thickness = 0.75mm.

- 6 Elastomer Guide: Cirlex or equivalent
Thickness = 0.725mm.

- 7 Ball Guide: Kapton polyimide.

- 8 Socket base screw: Socket head cap, Alloy steel with
black oxide finish, 0-80 fine thread , 12.7mm long.

- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine
thread.

- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.

- 11 Backing Plate: Black anodized Aluminum.
Thickness = 6.35mm.

SG-BGA-6015 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: H

Drawing: Meghann Fedde

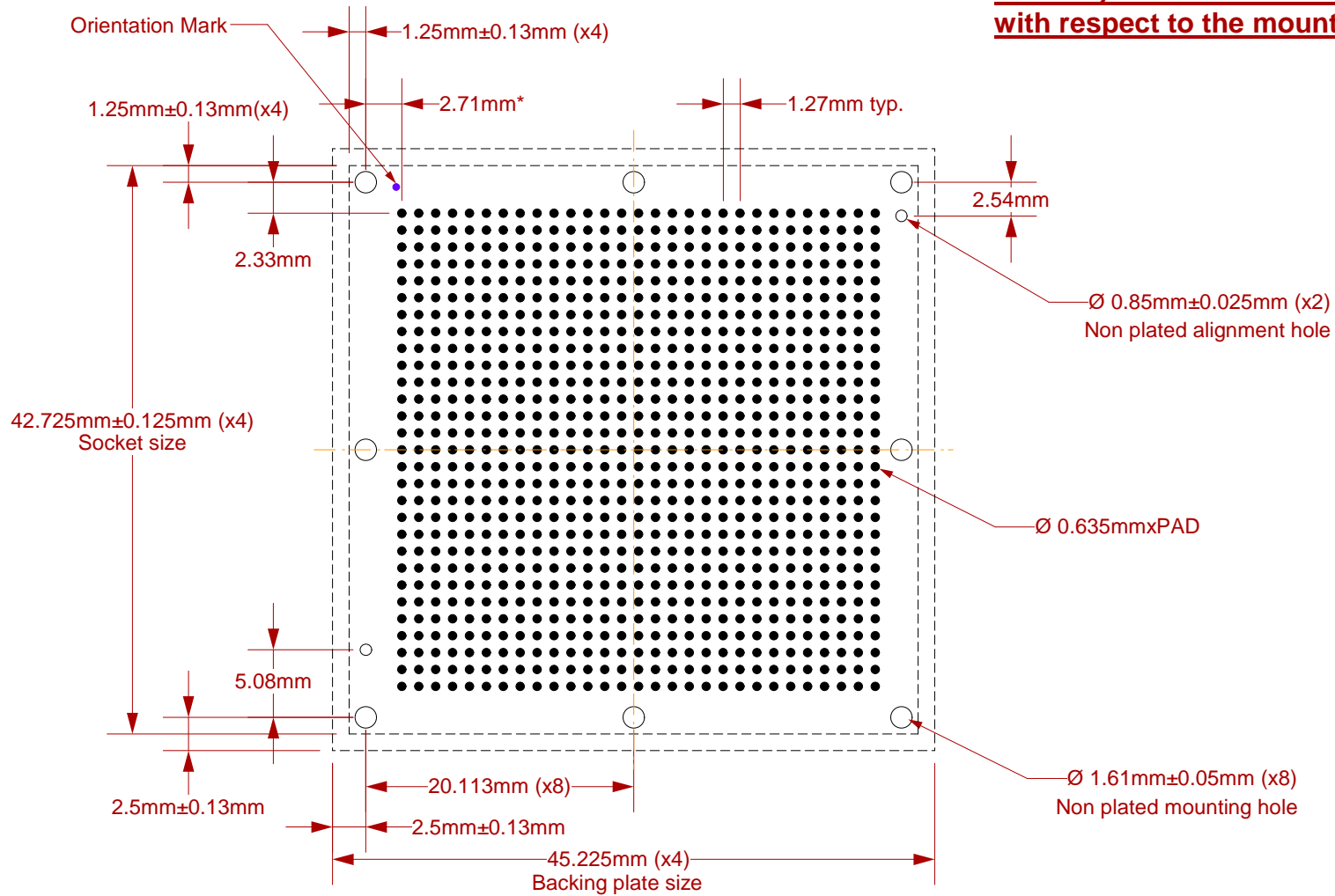
Date: 8/20/01

File: SG-BGA-6015 Dwg.mcd

Modified: 11/3/09, MAF

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes. It is offset by 0.375mm to the right of center with respect to the mounting holes**




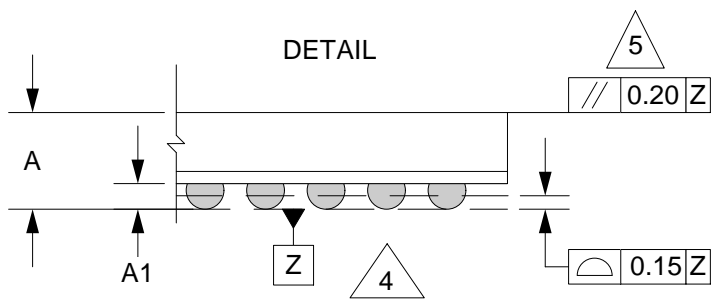
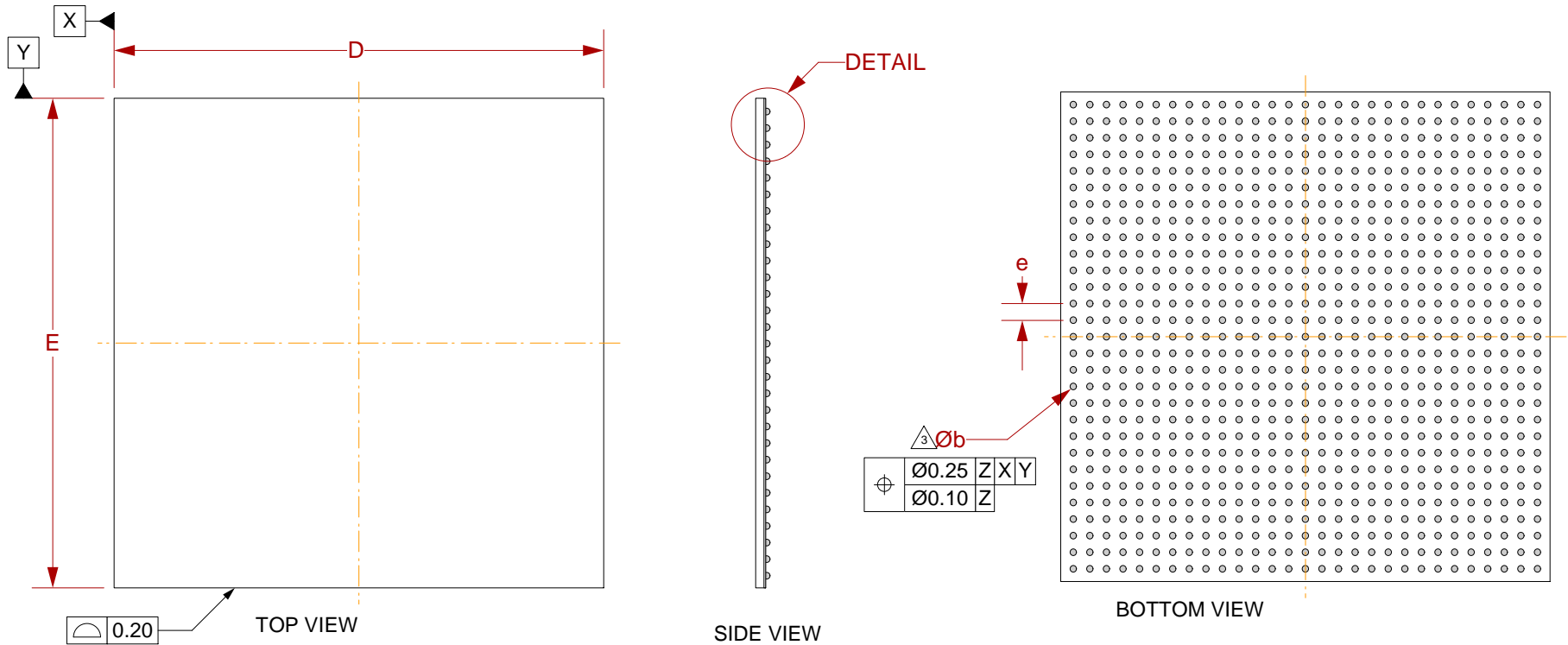
Target PCB Recommendations

Total thickness: 2.4mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


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	<p>Drawing: Meghann Fedde</p>	<p>Date: 8/20/01</p>		<p>Modified: 11/3/09, MAF</p>
<p>File: SG-BGA-6015 Dwg.mcd</p>				



- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.6	0.7
b		0.85
D	37.50 BSC	
E	37.50 BSC	
e	1.27 BSC	

Array: 29x29

 <p>SG-BGA-6015 Drawing</p> <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Status: Released	Scale: -	Rev: H
	Drawing: Meghann Fedde		Date: 8/20/01
	File: SG-BGA-6015 Dwg.mcd		Modified: 11/3/09 MAF

